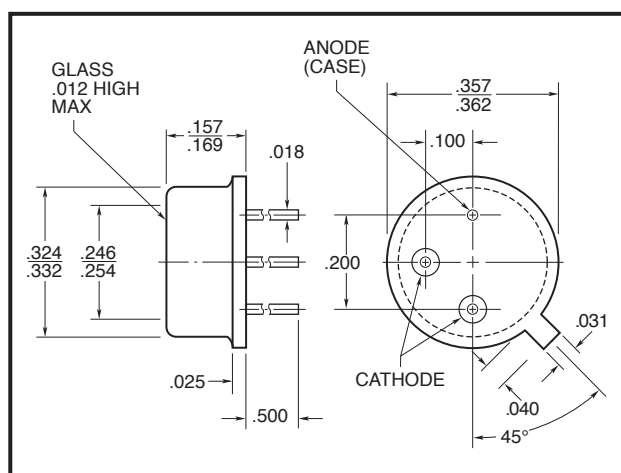




FEATURES

- Ultra high power output
- Four wire bonds on die corners
- Very uniform optical beam
- Standard 3-lead TO-39 hermetic package
- Chip size .030 x .030 inches

All surfaces are gold plated. Dimensions are nominal values in inches unless otherwise specified. Two cathode pins **must be** externally connected together.



ELECTRO-OPTICAL CHARACTERISTICS AT 25°C

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Total Power Output, P_o	$I_F = 500\text{mA}$ $I_F = 10\text{A}$	60	75 1000		mW
Radiant Intensity, I_e	$I_F = 500\text{mA}$		60		mW/sr
Peak Emission Wavelength, λ_p	$I_F = 50\text{mA}$		880		nm
Spectral Bandwidth at 50%, $\Delta\lambda$			80		nm
Half Intensity Beam Angle, θ			110		Deg
Forward Voltage, V_F	$I_F = 500\text{mA}$		1.65	2	Volts
Reverse Breakdown Voltage, V_R	$I_R = 10\mu\text{A}$	5	30		Volts
Capacitance, C	$V_R = 0\text{V}$		90		pF
Rise Time			0.7		μsec
Fall Time			0.7		μsec

ABSOLUTE MAXIMUM RATINGS AT 25°C CASE

Power Dissipation ¹	1000mW
Continuous Forward Current	500mA
Peak Forward Current (10 μs , 400Hz) ²	10A
Reverse Voltage	5V
Lead Soldering Temperature (1/16" from case for 10sec)	260°C

¹Derate per Thermal Derating Curve above 25°C

²Derate linearly above 25°C

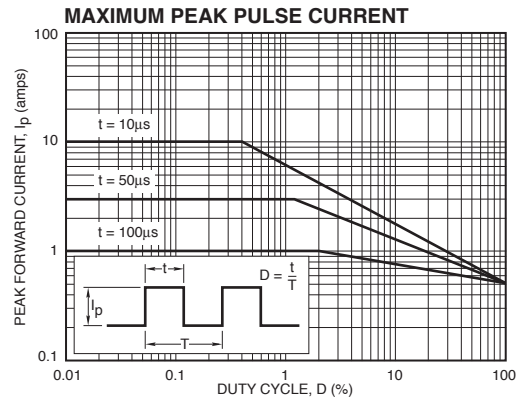
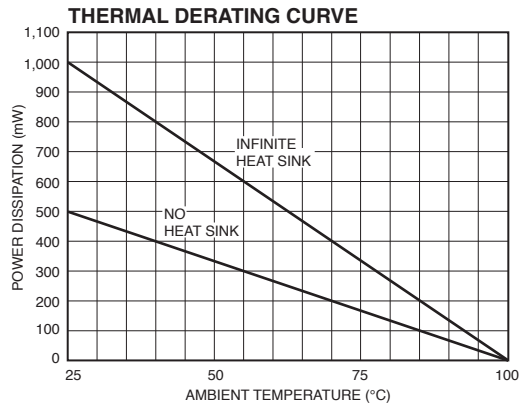
THERMAL PARAMETERS

Storage and Operating Temperature Range	-55°C to 100°C
Maximum Junction Temperature	100°C
Thermal Resistance, R_{THJA} ¹	145°C/W Typical
Thermal Resistance, R_{THJA} ²	75°C/W Typical

¹Heat transfer minimized by measuring in still air with minimum heat conducting through leads

²Air circulating at a rapid rate to keep case temperature at 25°C

MAXIMUM RATINGS



TYPICAL CHARACTERISTICS

